

AP98T03GP-VB Datasheet N-Channel 30 V (D-S) MOSFET

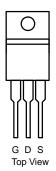
PRODUCT SUMMARY					
V _{DS} (V)	30				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.001				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0016				
I _D (A)	260				
Configuration	Single				

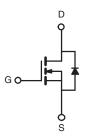
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- Package with Low Thermal Resistance
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC









N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	30	V	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current	T _C = 25 °C	1	260		
	T _C = 125 °C	- I _D	120 ^a		
Continuous Source Current (Diode Conduction) ^a	I _S	120	Α		
Pulsed Drain Current ^b		I _{DM}	680		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	82		
Single Pulse Avalanche Energy		E _{AS}	336	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	P _D	375	W	
	T _C = 125 °C	ГD	125	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	40	°C/W		
Junction-to-Case (Drain)		R _{thJC}	0.4	C/VV		

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static	•							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		30	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$		1.5	2.0	2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-		± 100	nA	
		V _{GS} = 0 V	V _{DS} = 30 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 30 V, T _J = 125 °C	-		50	μΑ	
		V _{GS} = 0 V	V _{DS} = 30 V, T _J = 175 °C	-		250		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	120		-	Α	
		V _{GS} = 10 V	I _D = 30 A	-	0.001	-	Ω	
Dunin Course On Chata Basistanas		V _{GS} = 10 V	I _D = 30 A, T _J = 125 °C	-	0.0023	-		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 30 A, T _J = 175 °C	-	0.0028	-		
		V _{GS} = 4.5 V	I _D = 20 A	-	0.0016	-		
Forward Transconductanceb	9fs	V _{DS} = 15 V, I _D = 30 A		-	190	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}		V _{GS} = 0 V V _{DS} = 15 V, f = 1 MHz	-	12484	15605	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$		-	2204	2755		
Reverse Transfer Capacitance	C _{rss}]		-	860	1075		
Total Gate Charge ^c	Qg				179	270		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 10 \text{ V}, I_{D} = 120 \text{ A}$	-	34	-	nC	
Gate-Drain Charge ^c	Q _{gd}	1		-	21	-		
Gate Resistance	R_{g}	f = 1 MHz		0.59	1.19	1.79	Ω	
Turn-On Delay Time ^c	t _{d(on)}	V_{DD} = 15 V, R_L = 0.3 Ω I_D \cong 50 A, V_{GEN} = 10 V, R_g = 1 Ω		-	18	27		
Rise Time ^c	t _r			-	11	17	- ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	64	96		
Fall Time ^c	t _f			-	11	17		
Source-Drain Diode Ratings and Char-	acteristics ^b				•			
Pulsed Current ^a	I _{SM}			-	-	480	Α	
Forward Voltage	V _{SD}	I _F = 60 A, V _{GS} = 0 V		-	0.81	1.5	V	

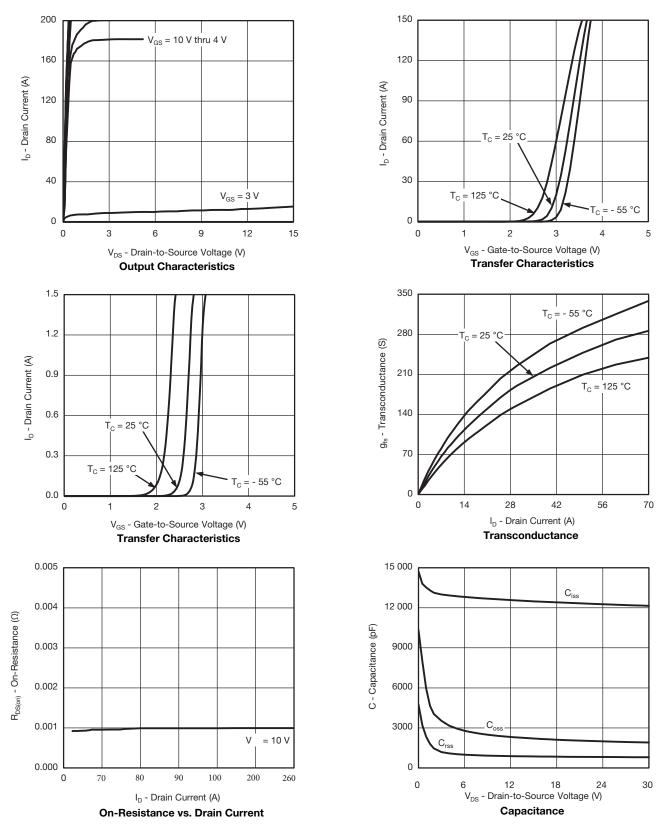
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

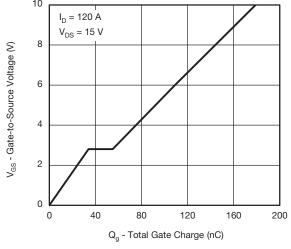


TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

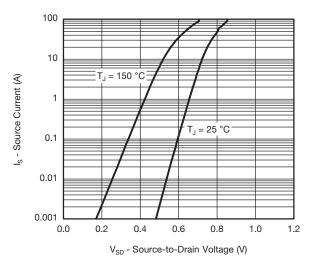




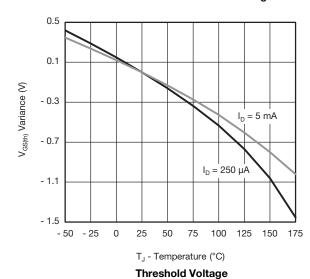
TYPICAL CHARACTERISTICS ($T_A = 25 \, ^{\circ}\text{C}$, unless otherwise noted)



Gate Charge

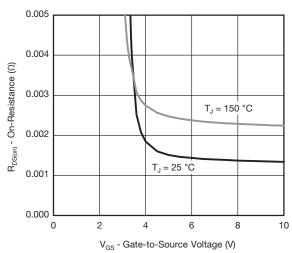


Source Drain Diode Forward Voltage

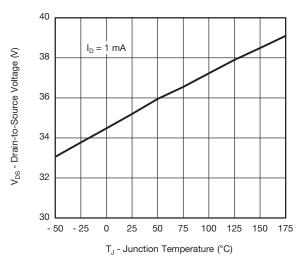


2.0 V_{GS} = 10 V $I_{D} = 30 \text{ A}$ 1.7 R_{DS(on)} - On-Resistance (Normalized) 1.4 1.1 0.8 0.5 - 50 - 25 0 25 50 75 100 125 150 175 T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature



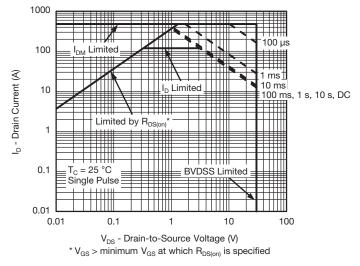
On-Resistance vs. Gate-to-Source Voltage



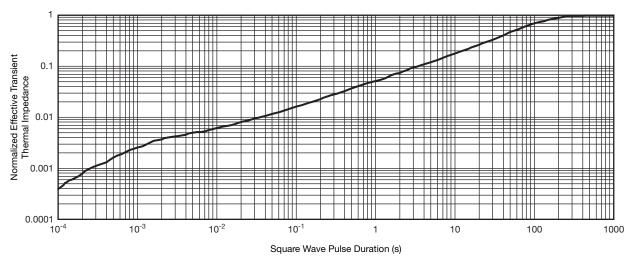
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25 \, ^{\circ}C$, unless otherwise noted)



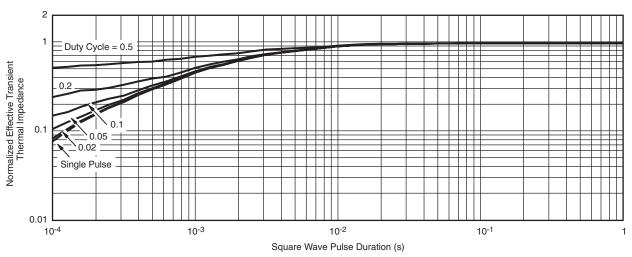
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

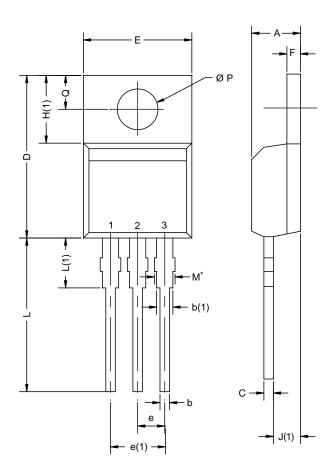
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-220AB



	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØР	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

Notes

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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